FAIRCHILD

SEMICONDUCTOR®

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FT8010
Reset Timer with Configurable Delay Time

Features

- Long Delay Configurable to 7.5 or 11.25 Seconds

- Primary and Secondary Input Reset Pins

- Push-Pull and Open-Drain Output Pins

- 2.0V to 5.0V Operation

- Packaged in 10-Lead UMLP (1.4mm x 1.8mm) and 8-Lead MLP (2.0mm x 2.0mm) Packages

Description

The FT8010 is a timer for resetting a mobile device where long reset times are needed. The long time delay helps avoid unintended resets caused by accidental key presses. Two delays can be selected by hard-wiring the DSR pin: 7.5 ±20% seconds or 11.25 ±20% seconds.

The FT8010 has two identical inputs for single or dual switch resetting capability. The device has two outputs: a push-pull output with 0.5mA drive and an open-drain output with 0.5mA pull-down drive.

FT8010 draws minimal I_{CC} current when inactive and functions over a wide 2.0V to 5.0V power supply range.

Ordering Information

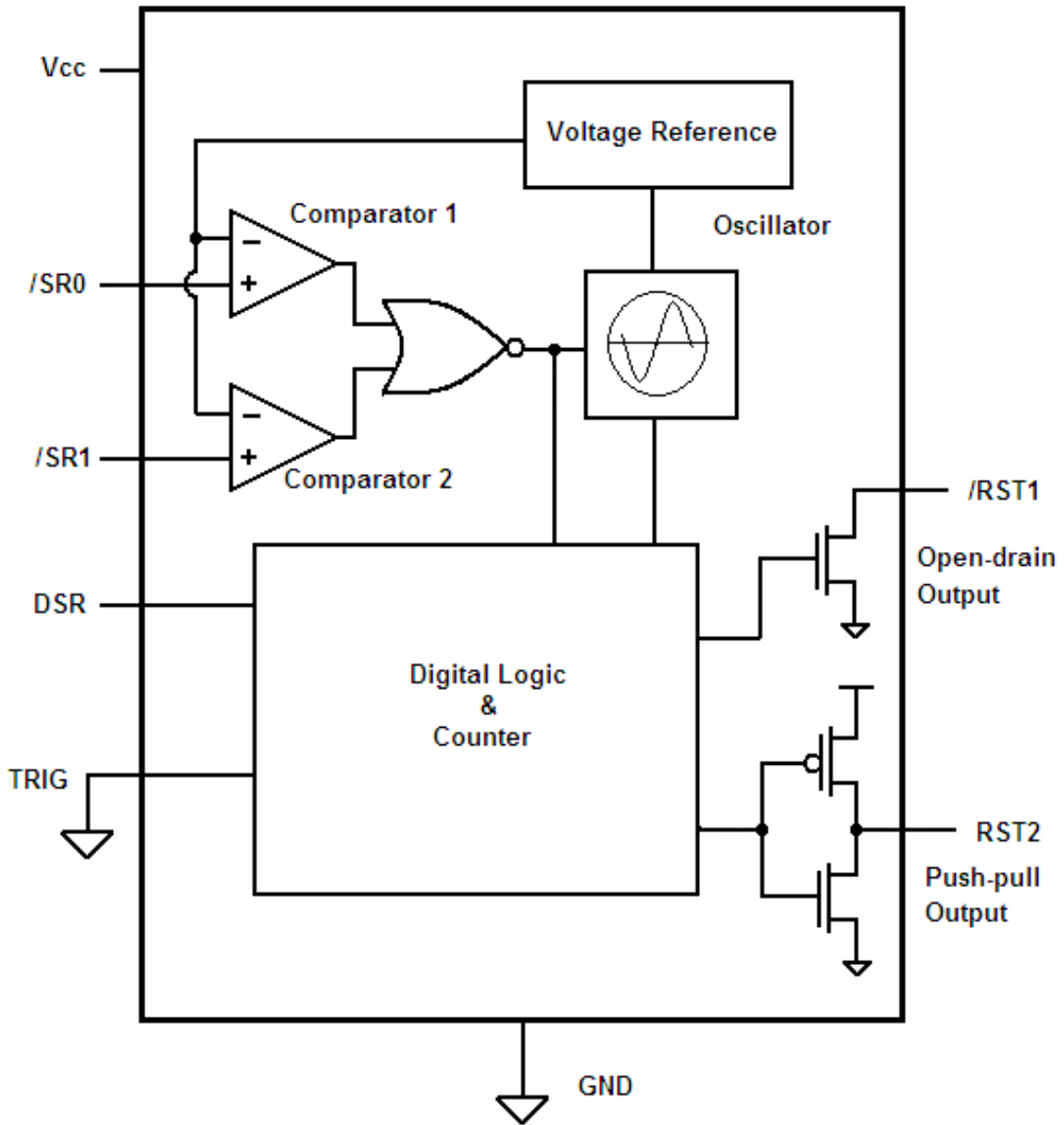| Part Number	Operating Temperature Range	Package	Packing Method
FT8010UMX	-40°C to +85°C	10-Lead Ultrathin MLP, 1.4 x 1.8 x 0.55mm Package, 0.40mm Pitch	5000 Units Tape and Reel
FT8010MPX	-40°C to +85°C	8-Lead, MLP 2.0 x 2.0 x 0.8mm Package, 0.5mm Pitch	3000 Units Tape and Reel

Block Diagram

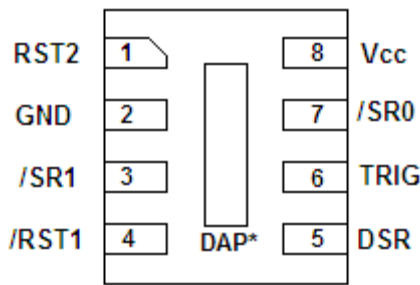Figure 1.   Block Diagram

Pin Configuration

Figure 2.   MLP Pin Configuration[1]
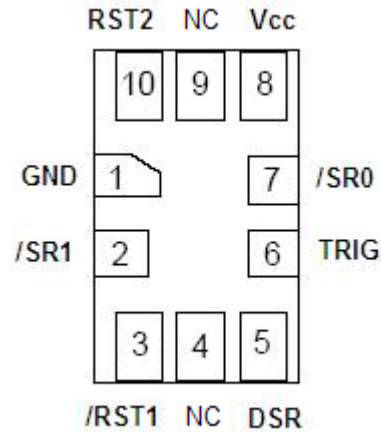**(Top Through View)**

Figure 3.   UMLP Pin Configuration[2]
(Top Through View)

Note:
1.   The DAP may be a no connect or it may be tied to ground.
2.   NC = No connect

Pin Definitions

MLP Pin #	UMLP Pin #	Name	Description
1	10	RST2	Push-Pull Output, Active HIGH
2	1	GND	Ground
3	2	/SR1	Secondary Reset Input, Active LOW
4	3	/RST1	Open-Drain Output, Active LOW
5	5	DSR	Delay Selection Input
6	6	TRIG	Test Pin, Tied to GND in Normal Use
7	7	/SR0	Primary Reset Input, Active LOW
8	8	V_{CC}	Power Supply
	4, 9,	NC	No Connect

Functional Description

The FT8010 reset timer uses an internal oscillator and a two-stage, 21-bit counter to determine when the output pins switch. Time N is set by the hard-wired logic level of the DSR pin. N is either 7.5 ±20% seconds for DSR=LOW or 11.25 ±20% seconds for DSR=HIGH.

Table 1.   FT8010 Truth Table

DSR	Reset Timer (+-20%)
0	7.5s
1	11.25s

The two input pins, /SR0 and /SR1, drive voltage comparators that compare the voltage on the input with the voltage set by the reference block. A low input signal on both /SR0 and /SR1 starts the oscillator. The oscillator sends data pulses to the digital core, which includes the counter. There are two scenarios for counting, as described below: short duration and long duration. In the short-duration scenario, outputs /RST1 and RST2 are not affected. In the long duration scenario, the outputs change state after time N. The outputs return to their original states when a HIGH input signal occurs on either /SR0 or /SR1.

The /RST1 output is an open-drain driver. When the count time exceeds time N, the /RST1 output drives LOW. The RST2 output is a push-pull driver. When the count time exceeds time N, the RST2 output drives HIGH.

The TRIG pin should be tied GND or LOW during normal operation. The TRIG pin is a test mode pin used for SCAN testing.

Application Note

IMPORTANT: The DSR pin must be tied to V_{CC} or GND to provide a HIGH or LOW voltage level. The voltage level on the DSR pin determines the length of the configurable delay. **It is important that the voltage level on the DSR pin not change during normal operation. The DSR must be tied to valid Vcc or GND before SR0 or SR1 buttons go LOW.**

Short Duration ($t_W < N$)

In this case, both input /SR0 and /SR1 are LOW for a duration t_W which is shorter than time N. When an input goes LOW, the internal timer starts counting. The input goes HIGH before time N. The timer stops counting and resets and no changes occur on the outputs (*see Figure 4).*

/SR0	/SR1	/RST1	/RST2	Description
⎍ (pulse low)	L	H	L	The timer starts counting when both inputs go LOW. The timer stops counting and resets when either input goes HIGH. No changes occur on the outputs, Both /SR0 and /SR1 need to be LOW to activate (start) the timer.
L	⎍ (pulse low)	H	L	
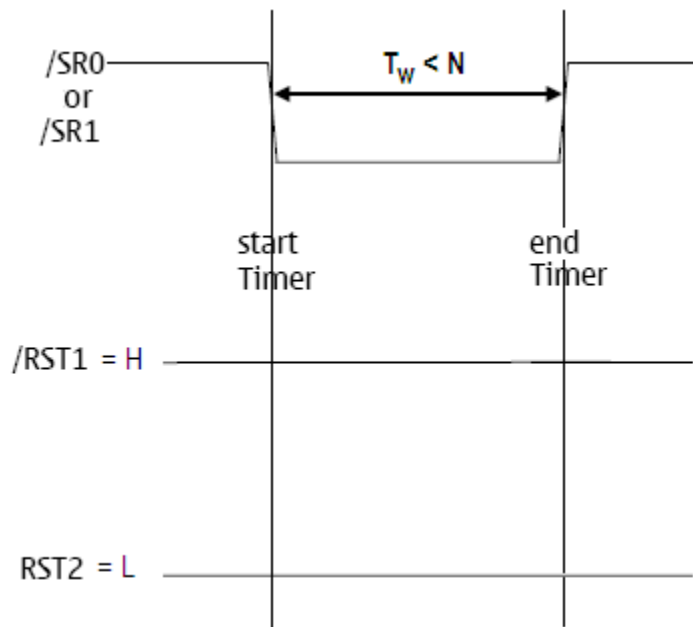
Figure 4.   Short Duration Waveform

Long Duration (t_W > N)

In this case, inputs /SR0 and /SR1 are LOW for a duration, t_W, which is longer than time N. When an input goes LOW, the internal timer starts counting. After time N, the outputs switch and the timer stops counting. The input goes HIGH sometime after N seconds. When the input goes HIGH, the timer resets and the outputs switch back to their original state after a propagation delay *(see Figure 5)*.

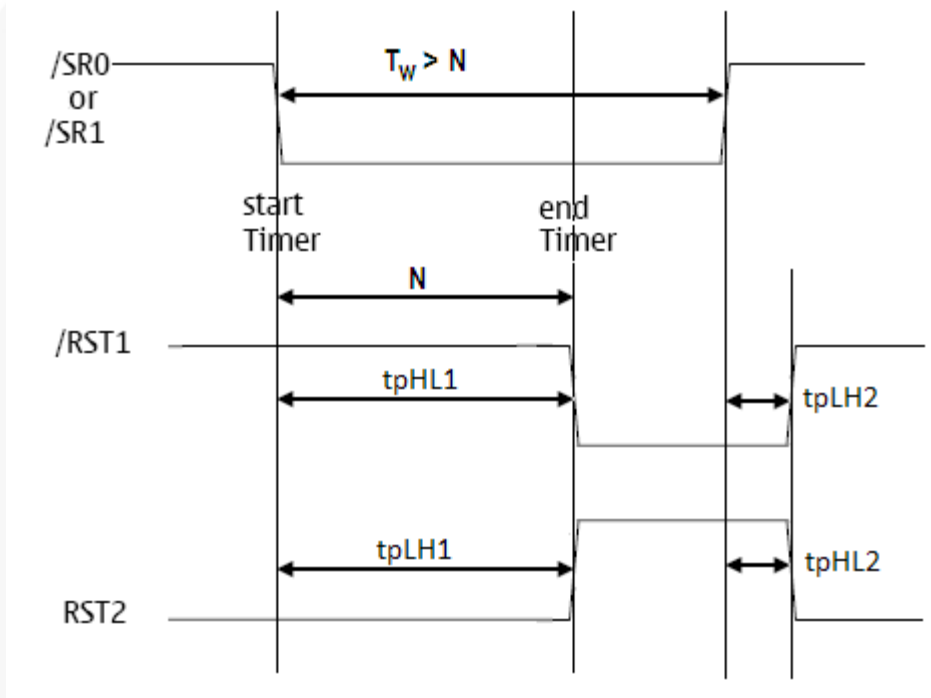| /SR0	/SR1	/RST1	RST2	Description
⌄	L	⌄	⌢	The timer starts counting when both inputs go LOW. After time N, the outputs switch. When either input goes HIGH, the timer resets and the outputs switch back to their original state. Both /SR0 and /SR1 need to be LOW to activate (start) the timer.
L	⌄	⌄	⌢	

Figure 5.   Long Duration Waveform

Note:
3.   Waveforms not drawn to scale (tpHL1, tpLH1 >> tpHL2, tpLH2)

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V_{CC}	Supply Voltage		-0.5	5.5	V
V_{IN}	DC Input Voltage	/SR0, /SR1, TRIG, DSR	-0.5	5.5	V
V_{OUT}	Output Voltage[4]	/RST1 HIGH or LOW	-0.5	5.5	V
		RST2 HIGH or LOW	-0.5	Vcc+0.5	
		/RST1, RST2, V_{CC}=0	-0.5	5.5	
I_{IK}	DC Input Diode Current	V_{IN} < 0V		-50	mA
I_{OK}	DC Output Diode Current	V_{OUT} < 0V		-50	mA
		V_{OUT} > V_{CC}		+50	
I_{OH}/I_{OL}	DC Output Source/Sink Current		-50	+50	mA
I_{CC}	DC V_{CC} or Ground Current per Supply Pin			±100	mA
T_{STG}	Storage Temperature Range		-65	+150	°C
T_J	Junction Temperature under Bias			+150	°C
T_L	Junction Lead Temperature, Soldering 10 Seconds			+260	°C
P_D	Power Dissipation			5	mW
ESD	Electrostatic Discharge Capability	Human Body Model, JESD22-A114		4	kV
		Charged Device Model, JESD22-C101		2	

Note:
4. I_O absolute maximum rating must be observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V_{CC}	Supply Voltage		1.8	5.0	V
t_{RFC}	V_{CC} Recovery Time After Power Down	V_{CC}=0V After Power Down, Rising to 0.5V	5		ms
V_{IN}	Input Voltage	/SR0, /SR1	0	5	V
V_{OUT}	Output Voltage	/RST1 HIGH or LOW	0	5	V
		RST2 HIGH or LOW	0	Vcc	
		/RST1, RST2, V_{CC}=0	0	5	
I_{OH}	DC Output Source Current	RST2, 1.8V ≤ V_{CC} ≤ 3.0V	-0.1		mA
		RST2, 3.0V ≤ V_{CC} ≤ 5.0V	-0.5		
I_{OL}	DC Output Sink Current	/RST1, RST2, V_{CC}=1.8V to 5.0V	+0.5		
T_A	Free Air Operating Temperature		-40	+85	°C
Θ_{JA}	Thermal Resistance	MLP-8		245	°C/W
		UMLP-10		200	

Note:
5. All unused inputs must be held at V_{CC} or GND.

DC Electrical Characteristics

T_A=-40°C to +85°C.

Symbol	Parameter	Conditions	V_{CC} (V)	Min.	Max.	Unit
V_{IH}	Input High Voltage	/SR0, /SR1	2.0 to 5.0	1.2		V
		DSR	2.0 to 5.0	0.65 x V_{CC}		
V_{IL}	Input Low Voltage	/SR0, /SR1	2.0 to 5.0		0.32	V
		DSR	2.0 to 5.0		0.25 x V_{CC}	
V_{OH}	High Level Output Voltage	RST2, I_{OH}=-100μA	1.8 to 3.0	0.8 x V_{CC}		V
		RST2, I_{OH}=-500μA	3.0 to 5.0	0.8 x V_{CC}		
V_{OL}	Low Level Output Voltage	RST2, I_{OL}=500μA	2.0 to 5.0		0.3	V
		/RST1, I_{OL}=500μA	1.8 to 5.0		0.3	
I_{IN}	Input Leakage Current	0V ≤ V_{IN} ≤ 5.0V	2.0 to 5.0		±1.0	μA
I_{CC}	Quiescent Supply Current (Timer Inactive)	/SR0 or /SR1=V_{CC}	2.0 to 5.0		20	μA
	Dynamic Supply Current (Timer Active)	/SR0=/SR1=0V	2.0 to 5.0		100	

AC Electrical Characteristics

T_A=-40°C to +85°C.

Symbol	Parameter	Conditions	V_{CC} (V)	Min.	Typ.	Max.	Unit
t_{PHL1}	Timer Delay, /SRn to /RST1,(DSR=0)	C_L=5pF, R_L=5KΩ See Figure 6	2.0 to 5.0	6.0	7.5	9.0	s
	Timer Delay, /SRn to /RST1, (DSR=1)	C_L=5pF, R_L=5KΩ See Figure 6	2.0 to 5.0	9.00	11.25	13.50	s
t_{PLH2}	Propagation Delay, /SRn to /RST1 (DSR=0 or 1)	C_L=5pF, R_L=5KΩ See Figure 6	2.0 to 5.0		220	310	ns
t_{PLH1}	Timer Delay, /SRn to RST2, (DSR=0)	C_L=5pF, R_L=10KΩ See Figure 7	2.0 to 5.0	6.0	7.5	9.0	s
	Timer Delay, /SRn to RST2, (DSR=1)	C_L=5pF, R_L=10KΩ See Figure 7	2.0 to 5.0	9.00	11.25	13.50	s
t_{PHL2}	Propagation Delay, /SRn to RST2 (DSR=0 or 1)	C_L=5pF, R_L=10KΩ See Figure 7	2.0 to 5.0		210	300	ns

Capacitance Specifications

T_A=+25°C.

Symbol	Parameter	Conditions	Typical	Unit
C_{IN}	Input Capacitance	V_{CC}=GND	4.0	pF
C_{OUT}	Output Capacitance	V_{CC}=5.0V	5.0	pF

AC Test Circuit and Waveforms

V_{CC}

V_{CC}

$R_L \, \Omega$

Input

$C_L \, pF$

$t_f = 3 \, ns$ $t_r = 3 \, ns$

t_W

V_{CC}

90%   90%

V_{mi} 50% V_{mi} 50%

Input

10%   10%

tpHL1   tpLH2

V_{CC}

Output V_{mo} 50%
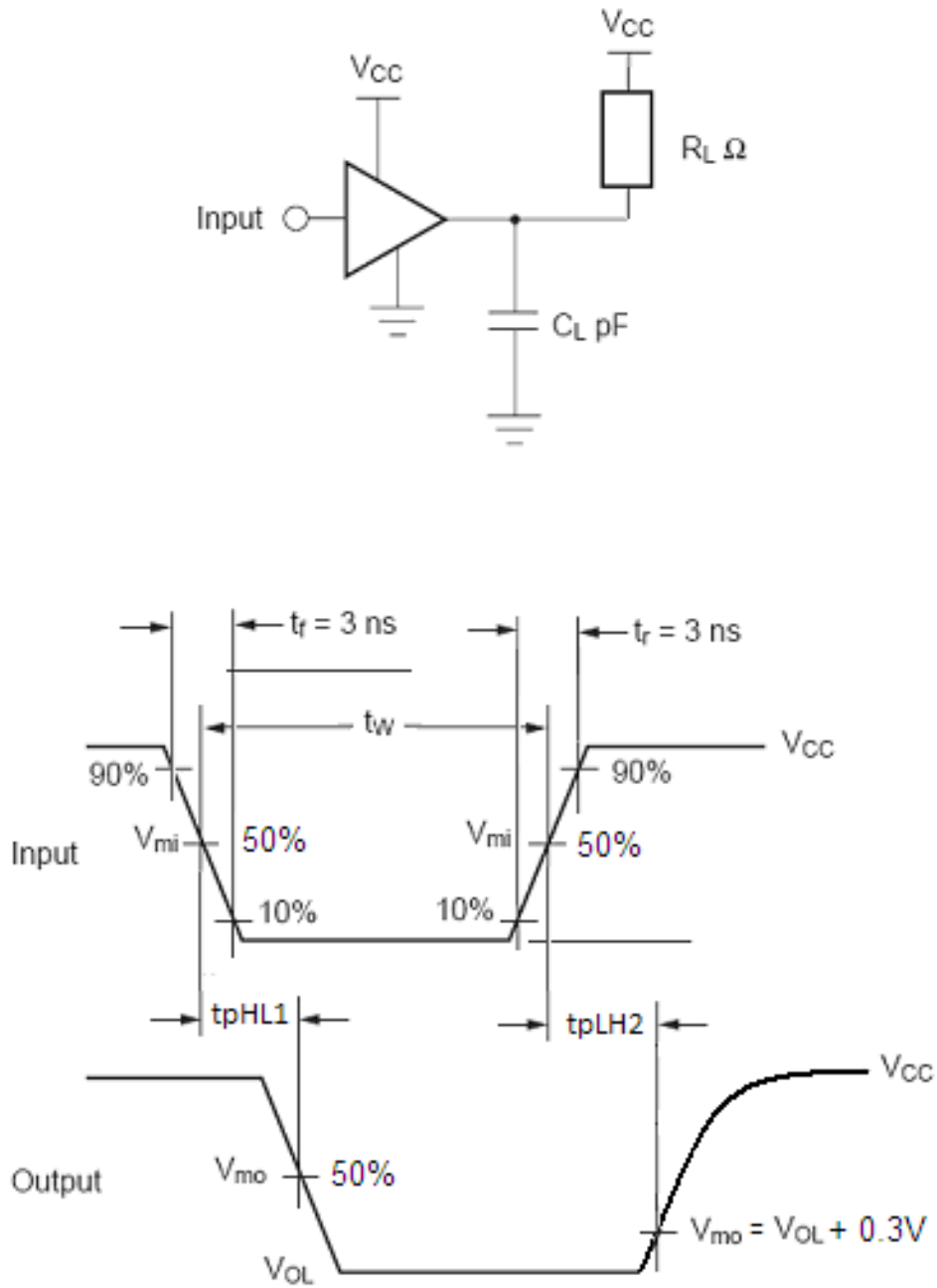
$V_{mo} = V_{OL} + 0.3V$

V_{OL}

Figure 6.   /RST1 Output

AC Test Circuit and Waveforms (Continued)
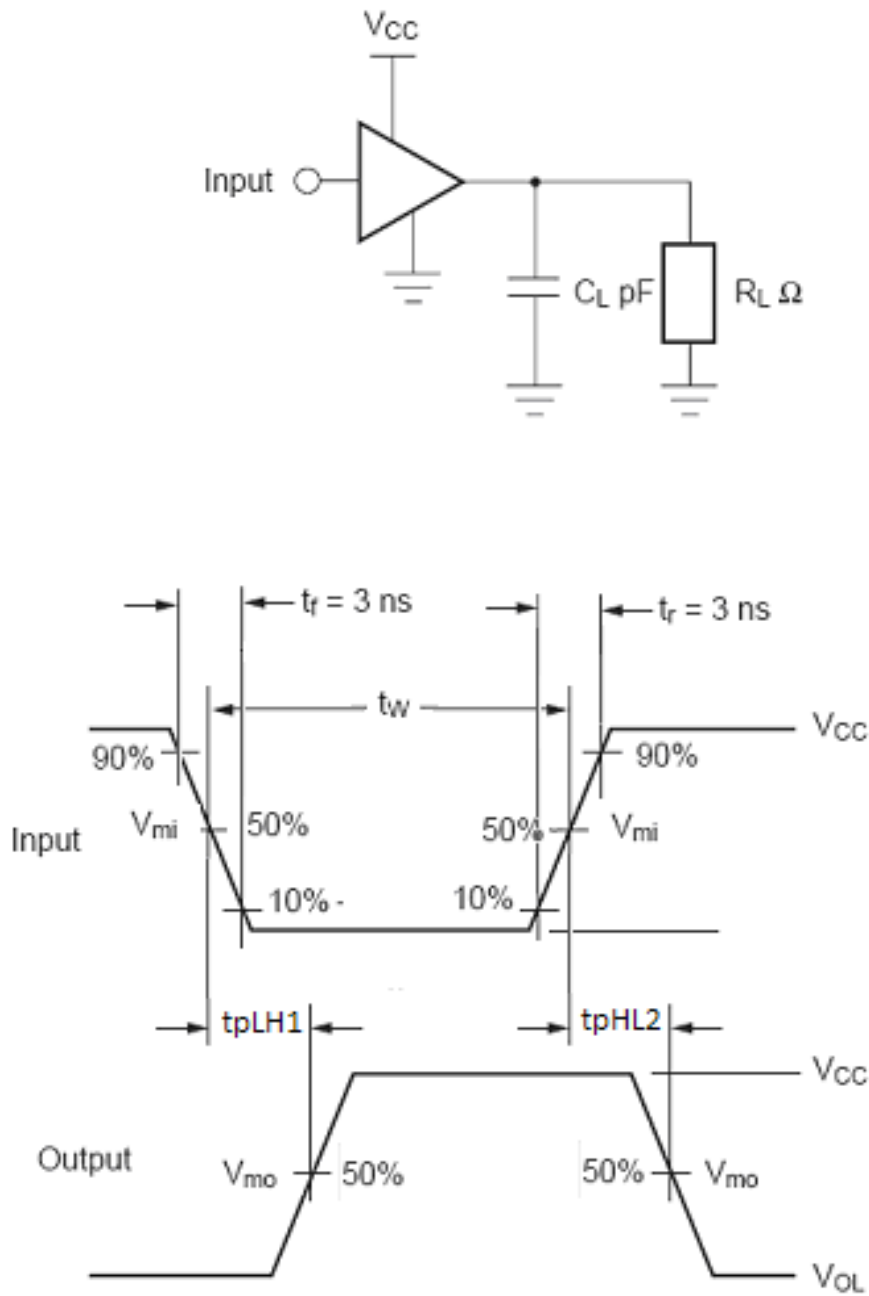
Figure 7.   RST2 Output

Physical Dimensions (Continued)

0.10 C
2X

2.00 → ▲ A

▲ B

PIN1
IDENT

2.00

0.10 C
2X

TOP VIEW

0.80 MAX

// 0.10 C

(0.20)

0.08 C

0.05
0.00

C

SEATING
PLANE

SIDE VIEW

0.25
0.15 8X Ⓐ

1   4   0.65 8X
0.45

PIN 1
IDENT

0.40 MAX

⊕ 0.10 Ⓜ C A B
0.05 Ⓜ C

8   5

0.50

1.35 MAX

BOTTOM VIEW

TOP LAYER
CU KEEP
OUT AREA

0.90

1.80

(0.90) 8X

0.50   (0.25) 8X

Ⓔ

OPTION #1: NO CENTER PAD

(1.35)

0.90

1.80

(0.35)

(0.90) 8X

0.50   (0.25) 8X

OPTION #2: WITH CENTER PAD

RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)

NOTES:

Ⓐ PACKAGE CONFORMS TO JEDEC MO-229,
VARIATION W2020D EXCEPT WHERE NOTED.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCES
PER ASME Y14.5M, 1994.

D. LAND PATTERN RECOMMENDATION BASED
ON PCB MATRIX CALCULATOR V2009.

Ⓔ IF CENTER PAD IS NOT SOLDERED TO, NO
EXPOSED METAL IS ALLOWED IN THE TOP
LAYER OF THE BOARD IN THE AREA SHOWN.

F. DRAWING FILENAME: MKT-MLP08Rrev2.

Figure 9.   8-Lead, Molded Leadless Package (MLP), 2.0 x 2.0 x 0.8mm

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